

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	1008	hasebe-hazuhide.in. or okada-mitsuhiro.in. or chiba- takashi.in. or ogawa-jun.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/22 09:06
S2	2	"20060213539"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/22 09:06
S3	26	("20030010354" "3865652" "5129958" "5963834" "6095158" "6121161" "6325857" "6375756" "6444037" "6468903" "6872323" "6942892").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/22 09:36
S4	1210	load\$3 with (substrate or semiconductor or wafer) with (temperature and pressure)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/22 10:21
S5	372	438/905.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/22 10:24
S6	3	S4 S5	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/22 10:24
S7	331	S4 "438".clas.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/22 10:30
S8	64	load\$3 with (substrate or semiconductor or wafer) near5 (temperature and (pressure with vacuum))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/22 10:37

S9	6296	loading near2 temperature	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/22 10:55
S10	51	load\$3 with (substrate or semiconductor or wafer) near5 (room with temperature) same(pressure with vacuum)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/22 11:03
S11	277	load\$3 with (substrate or semiconductor or wafer) near5 (room with temperature)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/22 11:06
S12	1366	438/758.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/22 11:28
S13	274	438/630.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/22 11:28
S14	372	438/905.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/22 11:28
S15	816	134/1.1.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/22 11:28
S16	2715	134/1.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/22 11:29
S17	1397	134/22.1.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/22 11:29

S18	764	134/22.11.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/22 11:29
S19	797	134/22.12.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/22 11:29
S20	2904466	@pd>="20070502"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/22 11:29
S21	254	(S12 or S13 or S14) S20	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/22 11:29
S22	94	load\$3 with (substrate or semiconductor or wafer) near5 (room with temperature) same (pressure)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/22 12:26
S23	277	load\$3 with (substrate or semiconductor or wafer) near5 (room with temperature)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/22 12:46
S24	12	S23.clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/22 13:06
S25	3	load\$3 with (substrate or semiconductor or wafer) near5 (room with temperature) with advantage	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/22 13:13
S26	277	load\$3 with (substrate or semiconductor or wafer) near5 (room with temperature)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/24 09:17

S27	93	unload\$3 with (substrate or semiconductor or wafer) near5 (room with temperature)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/24 09:19
S28	35	S26 S27	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/24 09:19
S29	48	("20010021000" "3978580" "4094058" "4653864" "4691995" "4775225" "5247377" "5263888" "5379139" "5406989" "5499128" "5507323" "5511591" "5539545" "5548429" "5642214" "5680189" "5692873" "5742370" "5757451" "5765889" "5852484" "5854664" "5861932" "5875922" "5952676" "5956112" "6001203" "6011609" "6016178" "6016181" "6055035" "6062241" "6068316" "6072157" "6152677" "6163357" "6219126" "6226067" "6236445" "6304306" "6304311" "6322116" "6337730" "6414733" "6634686").PN. OR ("6860533").URPN.	US-PGPUB; USPAT; USOCR	AND	ON	2008/07/24 09:25
S30	662	unload\$3 with (substrate or semiconductor or wafer) near5 temperature	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/24 09:27
S31	42	S26 S30	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/24 09:27
S32	7	S31 not S28	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/24 09:27

S33	2	"6143080".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/24 09:30
S34	890	load\$3 with (substrate or semiconductor or wafer or (work adj piece)) with ((room with temperature) or (temperature deg\$4))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/24 09:34
S35	190	unload\$3 with (substrate or semiconductor or wafer or (work adj piece)) with ((room with temperature) or (temperature deg\$4))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/24 09:35
S36	104	S34 S35	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/24 09:35
S37	31864939	@pd<"20030325"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/24 09:35
S38	46	S36 S37	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/24 09:35
S39	37	S36 S37 (pressure or vacuum)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/24 09:36
S40	312750	load\$3 with (pressure or vacuum)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/24 09:39
S41	9	S38 S40	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/24 09:39

S42	7970	118/715.ccls. or 118/724. ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/24 09:42
S43	54	S34 S42	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/24 09:43
S44	20	S43 S37	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/24 09:45
S45	9	S43 S37 unload\$5	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/24 09:49

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